



32nd Annual ELECTRICAL OVERSTRESS/ ELECTROSTATIC DISCHARGE SYMPOSIUM

OCT 3 - 8, 2010

John Ascuaga's Nugget Resort

Reno, Nevada, USA

CALL FOR PAPERS

About the EOS/ESD Symposium

The ESD Association, in cooperation with the IEEE, is sponsoring the 32nd Annual Symposium on Electrical Overstress (EOS) and Electrostatic Discharge (ESD) effects. The Symposium will be dedicated to the understanding of issues related to electrical transients and electrical overstress, and the application of this knowledge to the solution of problems in consumer, industrial and military applications, including electronic components and manufacturing, as well as in systems, subsystems and equipment.

Technical Papers

The Technical Program Committee solicits paper contributions, including data and analysis that advance the state-of-the-art knowledge, enhance or review the general knowledge, or discuss new topics related to EOS/ESD. Paper Presentations at the Symposium will be in electronic Power Point® format.

Abstracts

Authors must submit a 50-word abstract and 4-page (maximum) summary of their work. The summary must clearly state the purpose, results (e.g., data, diagrams, photographs, etc.), and conclusions of the work. Summaries must also include references to prior publications and state how the work enhances existing knowledge. Authors must designate the appropriate technical area related to their work and submission. See reverse for suggested, but not restricted, topic listings. **Authors are encouraged to use the abstract submission toolkit available on the ESD Association's website www.esda.org.**

Presentation of work at the International ESD Workshop (IEW) will not preclude an abstract submission, as long as the submission follows the EOS/ESD Symposium guidelines. If the IEW work is submitted to the EOS/ESD Symposium, it is required that the IEW work is expanded upon in the abstract submission for the EOS/ESD Symposium in order to be considered for acceptance.

Electronic Submissions

Abstract submissions shall be made electronically via an emailed PDF file to info@esda.org. **One file for each submission is required.**

Paper Acceptance

The Technical Program Committee will accept unpublished papers for peer review with the understanding that the author will not publish elsewhere the work prior to presentation at the Symposium. Accepted papers published in any form prior to presentation at the Symposium may result in the paper being withdrawn from the Symposium Proceedings. Authors must obtain appropriate company and government clearances prior to submitting their abstracts.

Paper Awards and Recognition

Awards are presented annually for the Symposium Outstanding Paper (selected by Symposium attendees), the Best Paper (selected by the Technical Program Committee), and the Best Student Paper. The Best Paper is considered for presentation at the RCJ EOS/ESD Symposium in Japan. Eligible student contributions for the Best Paper Award should be marked as such by the authors at the time of abstract submission.

Deadlines

The submission deadline is Friday, January 29, 2010. Late submissions will not be accepted. Abstracts not meeting guidelines may not be accepted. The final submission deadline for the finished papers will be Friday, July 2, 2010. **ESDA reserves the right to withdraw any paper not meeting the guidelines, including deadlines. Your paper MUST be submitted by the deadline.** Final papers will be limited to a maximum of 10 pages - guidelines will be provided after acceptance of the paper.

Contact addresses for questions or further information:

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Technically co-sponsored by the Electron Devices Society



Papers are solicited in the following areas:

I. Component Level EOS/ESD

- On-Chip Protection Devices & Techniques
- IC Design and Layout Issues
- ESD & Latchup, or other Reliability Aspects
- ESD in Advanced Technologies (Multi-gate, SOI, SiGe, Compound Semiconductors, Carbon Nano-tubes, etc.)
- EOS/ESD Failure Analysis
- Transmission Line Pulse and Other Testing Methods
- Processing Issues and Effects
- New ESD Phenomena in MEMS (Microelectromechanical Systems)
- ESD Device and Circuit Simulation
- Modeling and Physics of EOS/ESD
- RF Devices and Circuits
- High Voltage, High Power Technologies (BiCMOS, HV CMOS)

II. System Level EOS/ESD

- Simulators, Calibration and Correlation
- Optical Networks ESD
- ESD Detection and Measurement Techniques
- ESD Electronic Design Automation (EDA)
- Case Studies, Reviews and Analysis
- Test Methods and Procedures
- Modeling and Simulation

III. EOS/ESD Factory Level and Materials Technology

- Packaging and Handling
- Test Methods and Procedures
- Air Ionization and Uses
- Facility Design
- ESD Control Materials
- Use of Antistatic Materials
- Case Studies, Reviews and Analysis
- Transient ESD/EMI Induced Upset
- Troubleshooting Techniques
- Management Issues (cost/benefit analyses, etc.)
- ESD Shunting Packaging Technology
- Chemistry

IV. Electrostatic Considerations

- Biomedical & Chemical Industry Electrostatic Control
- ESD Control in Explosives and Pyrotechnics
- Aircraft, Spacecraft and Avionics ESD
- Graphic Arts Electrostatic Control
- Oil/Petroleum Industry Electrostatic Control
- Other ESD Topics

V. Magnetic Recording Heads and Ultra Sensitive Devices

- Testing and Analysis
- Special Considerations for Extremely Sensitive Devices
- Protection Techniques
- Failure Analysis Techniques and Interpretations

VI. ESD Standards – Components, System, Factory & Materials

- Test Methods and Procedures
- Standards - Comparisons and Analysis
- Round-Robin Testing, Results and Analysis
- Case Studies

Accepted papers covering selected topics may be considered for review for possible publication in a special issue of either the *IEEE Transactions on Components, Packaging and Manufacturing Technology*, the *Journal of Electrostatics*, the *Micro-Electronics Reliability Journal*, *IEEE Transactions on Device and Materials Reliability (TDMR)*, or other appropriate publications.

2010 EOS/ESD Symposium
c/o ESD Association
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